Improved Manufacturing of Solid State Lasers via Patterning of Photonic Crystals

Tech ID: 22342 / UC Case 2005-144-0

BRIEF DESCRIPTION

A method of fabricating solid state lasers with embedded structures for improved performance via patterning.

BACKGROUND

There is a need to improve the performance of horizontal emitting, vertical emitting, beam shaped and distributed feedback lasers. Traditionally, photonic crystals placed on the surface of the devices have been used to improve performance.

DESCRIPTION

Researchers at UCSB have developed a method of fabricating solid state lasers with embedded structures for improved performance via patterning. The patterned layer(s) may be engineered to act as a mirror, optical confinement layer, grating, wavelength selective element, beam shaping element, etc. for the active layers. The primary advantage of this technology is that it provides for fabrication of all the needed functionality in one lithography step via patterning.

ADVANTAGES

▶ Improved performance of the laser
▶ Improved contact structures and reduced waveguiding loss by contact electrodes
▶ Fabrication via one lithography step makes this invention easily manufacturable at low cost

APPLICATIONS

▶ Fiber optic networks
▶ Instrumentation lasers
▶ Optical spectroscopy

This technology is available for licensing.

PATENT STATUS

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<th>Type</th>
<th>Number</th>
<th>Dated</th>
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<tr>
<td>United States Of America</td>
<td>Issued Patent</td>
<td>7,723,745</td>
<td>05/25/2010</td>
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ADDITIONAL TECHNOLOGIES BY THESE INVENTORS

▶ Method for Improved Surface of (Ga,Al,In,B)N Films on Nonpolar or Semipolar Subtrates
▶ High Efficiency LED with Optimized Photonic Crystal Extractor
▶ Enhanced Optical Polarization of Nitride LEDs by Increased Indium Incorporation
▶ Etching Technique for the Fabrication of Thin (Al, In, Ga)N Layers
▶ Lateral Growth Method for Defect Reduction of Semipolar Nitride Films
▶ Flexible Arrays of MicroLEDs using the Photoelectrochemical (PEC) Liftoff Technique
▶ Vertical Cavity Surface-Emitting Lasers with Continuous Wave Operation
▶ Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-183)
▶ Internal Heating for Ammonothermal Growth of Group-III Nitride Crystals
Defect Reduction in GaN films using in-situ SiNx Nanomask
Enhanced Light Extraction LED with a Tunnel Junction Contact Wafer Bonded to a Conductive Oxide
Photonic Structures for Efficient Light Extraction and Conversion in Multi-Color LEDs
Highly Efficient Blue-Violet III-Nitride Semipolar Laser Diodes
Hybrid Growth Method for Improved III-Nitride Tunnel Junction Devices
Volumetric Hole Injection with Intentional V-Defects
Low Temperature Deposition of Magnesium Doped Nitride Films
Transparent Mirrorless (TML) LEDs
Laser Diode With Tunnel Junction Contact Surface Grating
Optimization of Laser Bar Orientation for Nonpolar Laser Diodes
Wavelength-Selective Phosphor Coating for Laser Lighting Devices
High Efficiency Semipolar AlGaN-Cladding-Free Laser Diodes
Method for Growing Self-Assembled Quantum Dot Lattices
Method for Enhancing Growth of Semipolar Nitride Devices
Ill-Nitride Tunnel Junction with Modified Interface
Improved Fabrication of Nonpolar InGaN Thin Films, Heterostructures, and Devices
Growth of High-Quality, Thick, Non-Polar M-Plane GaN Films
Increased Light Extraction with Multistep Deposition of ZnO on GaN
Method for Manufacturing Improved III-Nitride LEDs and Laser Diodes: Monolithic Integration of Optically Pumped and Electrically Injected III-Nitride LEDs
Selective-Area Mesoporous Semiconductors And Devices For Optoelectronic And Photonic Applications
High-Efficiency, Mirrorless Non-Polar and Semi-Polar Light Emitting Devices
Incorporating Temperature-Sensitive Layers in III-N Devices
Oxyfluoride Phosphors for Use in White Light LEDs
Technique for the Nitride Growth of Semipolar Thin Films, Heterostructures, and Semiconductor Devices
(In,Ga,Al)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
MOCVD Growth of Planar Non-Polar M-Plane Gallium Nitride
Reduced Dislocation Density of Non-Polar GaN Grown by Hydride Vapor Phase Epitaxy
Heterogeneously Integrated GaN on Si Photonic Integrated Circuits
(Al, In,Ga, B)N Device Structures
Reduction in Leakage Current and Increase in Efficiency of III-Nitride MicroLEDs
Methods for Fabricating III-Nitride Tunnel Junction Devices
3D Hole Injectors for InAlGaN Light-Emitting Diodes
Low-Droop LED Structure on GaN Semi-polar Substrates
Contact Architectures for Tunnel Junction Devices
Semi-polar LED/LD Devices on Relaxed Template with Misfit Dislocation at Hetero-interface
Photoelectrochemical Etching Of P-Type Semiconductor Heterostructures
Semipolar-Based Yellow, Green, Blue LEDs with Improved Performance
Growth of Semipolar III-V Nitride Films with Lower Defect Density
III-Nitride Tunnel Junction LED with High Wall Plug Efficiency
In-Situ Methods Of Preventing Interfacial Impurities And Dry Etch-Induced Damage In Regrown III-Nitride Structures
Enhanced Hole Injection by P-Type Active Region and Lateral Injection in InAlGaN LEDs
Solid Solution Phosphors for Use in Solid State White Lighting Applications
Tunable White Light Based on Polarization-Sensitive LEDs
Cleaved Facet Edge-Emitting Laser Diodes Grown on Semipolar GaN
Growth of High-Performance M-plane GaN Optical Devices
Packaging Technique for the Fabrication of Polarized Light Emitting Diodes
Improved Anisotropic Strain Control in Semipolar Nitride Devices
High Light Extraction Efficiency III-Nitride LED
Photoelectrochemical Etching for Chip Shaping Of LEDs
III-V Nitride Device Structures on Patterned Substrates
Hexagonal Wurtzite Type Epitaxial Layer with a Low Alkali-Metal Concentration
Method for Increasing GaN Substrate Area in Nitride Devices
Burying Impurities And Defects In Regrown III-Nitride Structures
Growth of Planar, Non-Polar, A-Plane GaN by Hydride Vapor Phase Epitaxy
Single or Multi-Color High Efficiency LED by Growth Over a Patterned Substrate
GaN-Based Thermoelectric Device for Micro-Power Generation
Limiting Strain-Relaxation in III-Nitride Heterostructures by Substrate Patterning

Packaging Technique for the Fabrication of Polarized Light Emitting Diodes
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Improved Manufacturing of Semiconductor Lasers
LED Device Structures with Minimized Light Re-Absorption
Growth of Planar Semi-Polar Gallium Nitride
Nonpolar (Al, B, In, Ga)N Quantum Well Design
UV Optoelectronic Devices Based on Nonpolar and Semi-polar AlInN and AlInGaN Alloys
Integration And Mass Transfer Of Microleds
Defect Reduction of Non-Polar and Semi-Polar III-Nitrides
Low-Cost Zinc Oxide for High-Power-Output, GaN-Based LEDs (UC Case 2010-150)
Suppression of Defect Formation and Increase in Critical Thickness by Silicon Doping
Wafer Bonding for Embedding Active Regions with Relaxed Nanofeatures
Enhancing Growth of Semipolar (Al,In,Ga,B)N Films via MOCVD